



PRINTED CIRCUIT BOARDS
INTERCONNECTION CARRIERS

State of the Art: PCB's

Revisio

Datum:

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01

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Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h + i
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04 025 FR4 35 L05.18 P05

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

04_025_FR4_L05.18_p05

Layers	in μ	Material	Build-Up	Assembly
Layer-1	35 μ	Copper		
	50 μ	Prepreg		
Layer-2	18 μ	Copper		
	50 μ	L-FR4		
Layer-3	18 μ	Copper		
	50 μ	Prepreg		
Layer-99	35 μ	Copper		

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